

Multilayer Ceramic Chip Capacitors

CGA4J3X7R1C225M125AB









TDK item description CGA4J3X7R1C225MT****

Applications	Automotive Grade	
Feature	General General (Up to 50V) AEC-Q200 AEC-Q200	
Series	CGA4(2012) [EIA 0805]	
Status	Production	



	Size
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
Recommended Land Pattern (PA)	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
Neconinented Land Factern (FB)	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
necommended Land Fattern (FC)	0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	2.2μF ±20%	
Rated Voltage	16VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	7.5%	
Insulation Resistance (Min.)	45ΜΩ	

Other		
Coldaring Mathed	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	Yes	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	2000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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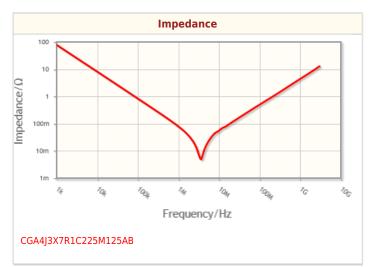


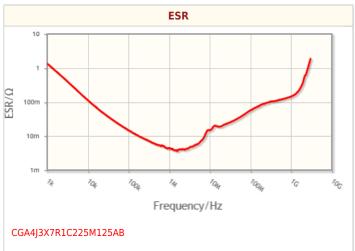


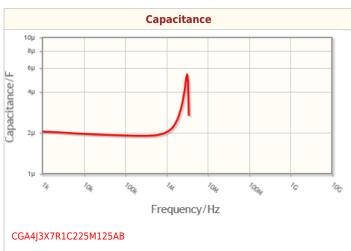


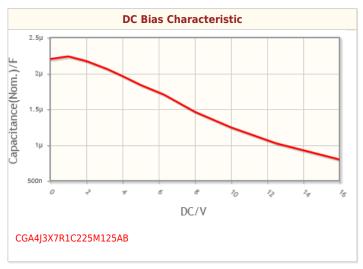


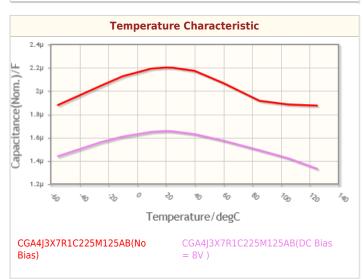
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

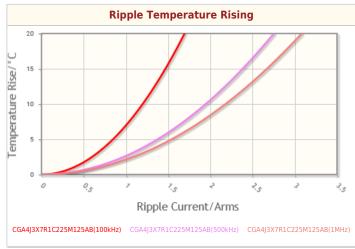












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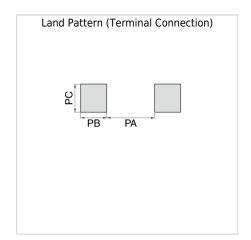








Associated Images



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